



RO3210[™] Circuit Materials

High Frequency Circuit Laminates



RO3210[™] high frequency circuit materials are ceramic-filled laminates reinforced with woven fiberglass. These materials are engineered to offer exceptional electrical performance and mechanical stability at competitive prices. The RO3200[™] series high frequency materials were designed as an extension of the RO3000[°] series high frequency circuit materials with one distinguishing characteristic - **improved mechanical stability.**

RO3200 series laminates combine the surface smoothness of a non-woven PTFE laminate, for finer line etching tolerances, with the rigidity of a woven-glass PTFE laminate. These materials can be fabricated into printed circuit boards using standard PTFE circuit board processing techniques as described in the application note, "Fabrication Guidelines for RO3000 Series High Frequency Circuit Materials." The dielectric constant of RO3210 high frequency circuit materials is 10.2 with a dissipation factor of 0.0027.

RO3200 series laminates are manufactured under an ISO 9002 certified quality system.

Data Sheet



Features and Benefits Woven glass reinforcement

• Improves rigidity for easier handling

Uniform electrical and mechanical performance

• Ideal for complex multi-layer high frequency structures

Low in-plane expansion coefficient (matched to copper)

- Suitable for use with epoxy multi-layer board hybrid designs
- Reliable surface mounted assemblies

Excellent dimensional stability

High production yields

Economically priced

 Cost effective volume manufacturing

Surface smoothness

Allows for finer line etching tolerances

Some Typical Applications:

- Automotive collision avoidance systems
- Automotive global positions satellite antennas
- Wireless telecommunications
 systems
- Microstrip patch antennas for wireless communications
- Direct broadcast satellites
- Datalink on cable systems
- Remote meter readers
- Power backplanes
- LMDS and wireless broadband
- Base station infrastructure



Property	Typical Value ⁽¹⁾ RO3210	Direction	Unit	Condition	Test Method
Dielectric Constant, ε _r Process	10.2± 0.50	Z	-	10 GHz 23°C	IPC-TM-650 2.5.5.5 Clamped Stripline
$^{\mbox{\tiny [2]}}$ Dielectric Constant, $\epsilon_{\rm r}$ Design	10.8	Z	-	8 GHz - 40 GHz	Differential Phase Length Method
Dissipation Factor, tan $\boldsymbol{\delta}$	0.0027	Z	-	10 GHz 23°C	IPC-TM-650 2.5.5.5
Thermal Coefficient of ε_r	-459	Z	ppm/°C	10 GHz 0-100°C	IPC-TM-650 2.5.5.5
Dimensional Stability	0.8	X,Y	mm/m	COND A	ASTM D257
Volume Resistivity	10 ³		MΩ•cm	COND A	IPC 2.5.17.1
Surface Resistivity	10 ³		MΩ	COND A	IPC 2.5.17.1
Tensile Modulus	579 517	MD CMD	kpsi	23°C	ASTM D638
Water Absorption	<0.1	-	%	D24/23	IPC-TM-650 2.6.2.1
Specific Heat	0.79		J/g/K		Calculated
Thermal Conductivity	0.81	-	W/m/K	80°C	ASTM C518
Coefficient of Thermal Expansion (-55 to 288 °C)	13 34	X,Y, Z	ppm/°C	23°C/50% RH	IPC-TM-650 2.4.41
Td	500		°C	TGA	ASTM D3850
Color	Off White				
Density	3.0		gm/cm3		
Copper Peel Strength	11.0		pli	1 oz. EDC After Solder Float	IPC-TM-2.4.8
Flammability	V-0				UL 94
Lead Free Process Compatible	YES				

NOTES:

[1] References: Internal T.R.'s 1430, 2224, 2854. Tests at 23°C unless otherwise noted. Typical values are a representation of an average value for the population of the property. For specification values contact Rogers Corporation.

[2] The design Dk is an average number from several different tested lots of material and on the most common thicknesses. If more detailed information is required please contact Rogers Corporation or refer to Roger's technical reports on the Rogers Technology Support Hub at http://www.rogerscorp.com/techub.

Standard Thickness	Standard Panel Size	Standard Copper Cladding
RO3210:	12″ X 18″ (305 X 457mm)	½ oz. (17μm) electrodeposited copper foil (HH/HH)
0.025" (0.64mm)	24" X 18" (610 X 457mm)	1 oz. (35μm) electrodeposited copper foil. (H1/H1)
0.050″ (1.28mm)		2 oz. (70μm) electrodeposited copper foil. (H2/H2)
		Other claddings may be available. Contact customer service.

The information in this data sheet is intended to assist you in designing with Rogers' circuit materials. It is not intended to and does not create any warranties express or implied, including any warranty of merchantability or fitness for a particular purpose. The user should determine the suitability of Rogers' circuit materials for each application.

The Rogers' logo, RO3200, RO3210 and RO3000 are trademarks of Rogers Corporation or one of its subsidiaries. © 2019 Rogers Corporation, Printed in U.S.A., All rights reserved. Revised 1443 080619 **Publication 92-109**